



**PRODUCT AND PROCESS CHANGE NOTIFICATION**  
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**ISSUE DATE:** 26-Nov-2013  
**NOTIFICATION:** 15880  
**TITLE:** S9S08AW16A/AW60/DZ60/DZ128/QD4 Burn-In Site Expansion to Trio Tech, Tianjin China (TTTJ)  
**EFFECTIVE DATE:** 25-May-2014

**DEVICE(S)**

MPN
G9S08AW32E5CFGE
G9S08AW32E5CFGGER
G9S08AW32E5VFGE
G9S08AW32E5VFGGER
G9S08AW32E7CFGE
G9S08AW32E7CFGGER
G9S08AW32E7VFGE
G9S08AW32E7VFGGER
G9S08DN48F2VLF
G9S08DN48F2VLFR
S9S08AW16AE0CFT
S9S08AW16AE0CFTR
S9S08AW16AE0CLD
S9S08AW16AE0CLDR
S9S08AW16AE0MFT
S9S08AW16AE0MLD
S9S08AW16AE0MLDR
S9S08AW16AE0VFT
S9S08AW16AE0VFTR
S9S08AW16AE0VLD
S9S08AW16AE0VLDR
S9S08AW16AE1CFT
S9S08AW16AE1CFTR
S9S08AW16AE1CLD
S9S08AW16AE1CLDR
S9S08AW16AE1MFT

S9S08AW16AE1MFTR
S9S08AW16AE1MLD
S9S08AW16AE1MLDR
S9S08AW16AE1VFT
S9S08AW16AE1VFTR
S9S08AW16E5CFDE
S9S08AW16E5CFGE
S9S08AW16E5CFGER
S9S08AW16E5MFGE
S9S08AW16E7CFDE
S9S08AW16E7CFDER
S9S08AW32E5CFDE
S9S08AW32E5CFDER
S9S08AW32E5CFGE
S9S08AW32E5CFGER
S9S08AW32E5MFGE
S9S08AW32E5MFGER
S9S08AW32E5VFGE
S9S08AW32E5VFGER
S9S08AW32E7CFDE
S9S08AW32E7CFDER
S9S08AW32E7CFGE
S9S08AW32E7CFGER
S9S08AW32E7MFGE
S9S08AW32E7MFGER
S9S08AW32E7VFDE
S9S08AW32E7VFGE
S9S08AW32E7VFGER
S9S08AW48E5CFGE
S9S08AW48E5CFGER
S9S08AW48E5MFGE
S9S08AW48E5VFDE
S9S08AW48E7CFGE
S9S08AW48E7CFGER
S9S08AW48E7MFGE
S9S08AW60E5MFDE
S9S08AW60E5MFGE
S9S08AW60E5MFGER

S9S08AW8AE0MLD
S9S08AW8AE0MLDR
S9S08DN16F2CLC
S9S08DN16F2CLF
S9S08DN32F2CLC
S9S08DN32F2CLF
S9S08DN32F2CLFR
S9S08DN32F2CLH
S9S08DN32F2CLHR
S9S08DN32F2MLC
S9S08DN32F2MLH
S9S08DN32F2VLC
S9S08DN32F2VLCR
S9S08DN32F2VLF
S9S08DN32F2VLFR
S9S08DN48F2CLF
S9S08DN48F2CLFR
S9S08DN48F2MLF
S9S08DN48F2MLFR
S9S08DN48F2MLH
S9S08DN48F2VLC
S9S08DN48F2VLF
S9S08DN48F2VLFR
S9S08DN60F2CLF
S9S08DN60F2CLH
S9S08DN60F2VLF
S9S08DN60F2VLH
S9S08DV128F2CLF
S9S08DV128F2CLFR
S9S08DV16F2CLC
S9S08DV16F2MLC
S9S08DV32F2MLC
S9S08DV32F2MLCR
S9S08DV32F2MLH
S9S08DV32F2VLC
S9S08DV32F2VLCR
S9S08DV48F2CLC
S9S08DV60F2CLH

S9S08DV60F2MLC
S9S08DV60F2MLF
S9S08DV96F2CLF
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S9S08DZ128F2CLH
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S9S08DZ16F2MLF
S9S08DZ16F2VLF
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S9S08DZ32F2CLHR
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S9S08DZ32F2MLF
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S9S08DZ32F2MLH
S9S08DZ32F2VLC
S9S08DZ32F2VLCR
S9S08DZ32F2VLF
S9S08DZ32F2VLH
S9S08DZ32F2VLHR
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S9S08DZ48F2CLFR
S9S08DZ48F2CLH
S9S08DZ48F2MLF
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S9S08DZ48F2VLF
S9S08DZ48F2VLFR
S9S08DZ60F2CLC
S9S08DZ60F2CLF

S9S08DZ60F2CLH
S9S08DZ60F2CLHR
S9S08DZ60F2MLC
S9S08DZ60F2MLCR
S9S08DZ60F2MLF
S9S08DZ60F2MLFR
S9S08DZ60F2MLH
S9S08DZ60F2MLHR
S9S08DZ60F2VLC
S9S08DZ60F2VLCR
S9S08DZ60F2VLH
S9S08DZ60F2VLHR
S9S08DZ96F2CLF
S9S08DZ96F2CLFR
S9S08DZ96F2CLH
S9S08DZ96F2CLHR
S9S08DZ96F2MLF
S9S08DZ96F2MLH
S9S08DZ96F2MLHR
S9S08DZ96F2VLF
S9S08DZ96F2VLFR
S9S08DZ96F2VLH
S9S08QD2J1CSC
S9S08QD2J1CSCR
S9S08QD2J1MSC
S9S08QD2J1MSCR
S9S08QD2J1VSC
S9S08QD2J1VSCR
S9S08QD4J1CSC
S9S08QD4J1CSCR
S9S08QD4J1MSC
S9S08QD4J1MSCR
S9S08QD4J1VSC
S9S08QD4J2CSC
S9S08QD4J2MSC
S9S08QD4J2MSCR

**AFFECTED CHANGE CATEGORIES**

- TEST SITE

**DESCRIPTION OF CHANGE**

Freescale Semiconductor is announcing the burn in site expansion from KESC, Tianjin China Facility to Trio Tech, Tianjin, China (TTTJ) Facility for the products listed below:

<b>Product</b>	<b>Package Type</b>
S9S08AW16A	LQFP44/QFN48
S9S08AW60	LQFP44/QFN48
S9S08DZ60	LQFP32/LQFP48/LQFP64
S9S08DZ128	LQFP48/LQFP64
S8S08QD4	SOIC8

**REASON FOR CHANGE**

Qualification of Trio Tech, Tianjin, China (TTTJ) to improve manufacturing flexibility and customer support.

**ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)**

There is no impact on device form, fit, function or reliability.

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Freescale will consider specific conditions of acceptance of this change submitted within 30 days of receipt of this notice on a case by case basis. To request further data or inquire about the notification, please enter a [Service Request](#).

For sample inquiries - please go to [www.freescale.com](http://www.freescale.com)

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**QUAL DATA AVAILABILITY DATE:** 30-Oct-2013

**QUALIFICATION STATUS:** COMPLETED

**QUALIFICATION PLAN:**

The correlation plans include site comparisons for burn-in voltage, temperature and current, in addition to manufacturability assessments at the new site.

**RELIABILITY DATA SUMMARY:**

All voltage, temperature and current comparison data passed within acceptable levels. Correlation reports are attached.

**ELECTRICAL CHARACTERISTIC SUMMARY:**

Burn-in correlation only, electrical characterization is not required.

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**CHANGED PART IDENTIFICATION:**

None. Part marking will not change as burn-in site is not included in part marking.

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**ATTACHMENT(S):**

External attachment(s) FOR this notification can be viewed AT:

[15880 15880-Qualfication Report-  
Burn In Expansion S9S08AW16A AW60 DZ60 DZ128 QD4.pdf](#)

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